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NPN SILICON EPITAXIAL PLANAR TRANSISTORS

BC546_BC550





For switching and AF amplifier application

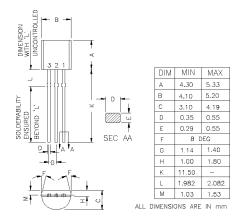
ABSOLUTE MAXIMUM RATINGS (T_a=25°C unless specified otherwise)

About the maximum trating of the 23 of the 33 specified otherwise)							
DESCRIPTION	SYMBOL	BC546	BC547 BC550	BC548 BC549	UNITS		
Collector Base Voltage	V_{CBO}	80	50	30	V		
Collector Emitter Voltage	V _{CEO}	65	45	30	V		
Emitter Base Voltage	V_{EBO}	6			V		
Collector Current (DC)	I _C		100		mA		
Collector Current - Peak	I _{CM}		200		mA		
Power Dissipation	P _{tot}	500			mW		
Storage Temperature	T _{stg}	- 65 to +150			°С		
Junction Temperature	T _j	150			∘C		

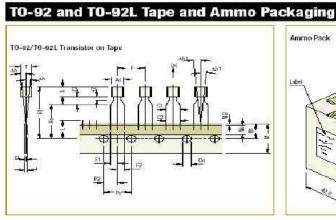
Characteristics at Ta = 25°C

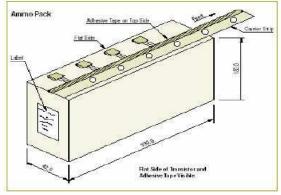
DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNITS
	h _{FE}	$I_C=2mA, V_{CE}=5V$	75	800	
DC Current Gain		Α	110	220	
	1.2	В	200	450	
		I _C =10mA, I _B =0.5mA	420	800 0.25	V
Collector Emitter Saturation Voltage	$V_{CE(Sat)}$	$I_{C}=100$ mA, $I_{B}=0.5$ mA	-	0.23	V
		$I_{C}=10011A$, $I_{B}=511A$ $I_{C}=2mA$, $V_{CE}=5V$	0.55	0.80	V
Base Emitter on Voltage	$V_{BE(on)}$		0.55		V
O-HtBO-t# O		I _C =10mA, V _{CE} =5V	-	0.77	•
Collector Base Cut off Current		$V_{CB}=30V$, $I_{E}=0$	-	15	nA
Emitter Base Cut off Current	I _{EBO}	V _{EB} =5V	-	100	nA
Collector Base Breakdown Voltage					
BC546	V (DD)CDO	I _C =100μA	80	-	
BC547, BC550			50	-	V
BC548, BC549			30	-	
Collector Emitter Breakdown Voltage	V _{(BB)CEO}				
BC546		I _C =2mA	65	-	
BC547, BC550			45	-	V
BC548, BC549			30	-	
Emitter Base Breakdown Voltage	$V_{(BR)EBO}$	I _E =10μA	6		V
Transition Frequency	f _T	I _C =10mA, V _{CE} =5V,f=100MHz	100	-	MHz
Collector Base Capacitance	C_cb	V _{CB} =10V, f=1MHz	-	6.0	pF

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Packaging	Specificatio	ons						
T & A: Tape and Ammo Pack;	T & R: Tape and Reel; Bulk:	Loose in Poly Bags; Tube	Tube and Carto	n; K : 1,000				
Package / Case Type	Packaging Type	\$td. Packing		Inner Carton		Outer Carton		
		Oty	Oty	Size L x W x H	Gross Weight	Qty	SizeLxWxH	Gross Weight
				(cm)	(Kg)		(cm)	(Kg)
T0-92	Bulk	1,000	5K	19 x 19 x 8	1.1	80K	43 x 40 x 35	20.0
	TAA	2 000	2K	32 x 4 5 x 20	0.7	dok	43 x 40 x 35	15.2





Tape Specifications

Item description	Symbo
Body width	A1
Body height	A
Body thickness	T
Pitch of component [©]	P
Feed hole pitch ⁶¹	Po
Feed hale center to component centre ^{sp}	P2
Comp. alignment, Side view ⁶⁹	Dh
Comp. alignment, Front view ⁶³	Oht
Tape width or	W
Hold down tape width ^{or}	Wio
Hole position	W1
Hold-down tape position	W2
Lead wire clinch height	Ho
Component height	Hi
Length of snipped leads	L
Feed hole diameter ^{cr}	Do
Total tape thickness ⁵⁴	t
Lead-to-lead distance ^{Cr}	F1, F2
Stand off	H2
Clinch height	Нз
Lead parallelismCr	C1-CZ
Pull-out force	(0)

Min	Nom	Max	Tol
4.45	0.0000000000000000000000000000000000000	5.20	-
4.32		5.33	
3.18		4.19	
	12.7		±1.0
	12.7		±0.3
	6.35		±0.4
	0	1.0	
	0	1.3	
	18		±0.5
	6		±0.2
-	9		+0.7 -0.5
0.0		0.7	
	1G		±0.5
		24.0	
		11.0	
	4		±0.2
		1.2	
2.4	3	2.7	
0.45		1.45	
		3.0	
		0.22	
614			

Min	Nom	Max	Tot
4.7		5.1	
7.8		8.2	
3.7		4.1	
-204	12.7		±0.3
	12.7		±0.2
	6.35		±0.3
	0		±1.0
	0		±1.0
	18.0		+1.0 -0.5
	6.0		±0.5
	9.0		±0.5
		1.0	
	16.0		±0.5
		29.0	
		11.0	
	4.0		±0.2
	0.2		±0.5
2.2		2.0	
0.45		1.45	
		4.0	
		0.22	
6N			

- Taping Specification
- Maximum alignment deviation between
- leads not to be greater than 0.20 mm. Maximum non-cumulative variation between tape feed holes shall not ex-1 mm in 20 pitches.
- Hold down tape not to exceed beyond the edge(s) carrier tape and there shall be no exposure of adhesive.
- No more than 3 consecutive missing compenents is permitted.
- A tape trailer, having at least three feed holes is required after the last
- compenent.

 Splices shall not interfere with the sprocket feed holes.
- §1 Currelative pitch error 1.0 mm/29 pitch.
- \$2 To be measured at bottom of cinch. \$3 At top of body. \$4 tt = 0.5 0.5 mm. Cr. Critical Dimension.

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Customer Notes BC546_BC550

TO-92 Plastic Package

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD is believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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